



SAFETEC and levelling compound

System IDEAL CLASSIC EPS 30



Without additional thermal insulation

<u>(</u>	0.78 m²K/W	Minimum thermal conductivity resistance to heated rooms according to DIN EN 1264	~ 25 kg / m ² Without floor covering	Category	()) EN 1991	EN 1991/NA	+ SIA 261
K		fulfilled			✓ A	✓ A2 A3	✓ A1
U	1.05 W/m²K	Heat transfer resistance $R_{s_i} = 0.17 \text{ m}^2\text{K/W}$ considered	$(q_k) \leq 2.0 \text{ kN / m}^2$				
						✓ B1 D1	—
	14 dB	Directional value according to DIN 4109 on solid ceilings	$Q_k \leq 2.0 \text{ kN}$ Single load				
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Level, smooth and load-bearing substrate required (increased requirements according to DIN 18202 Tab. 3, line 4).

Wooden beam ceilings must be torsionally rigid and sag-free L/300 = for a span of 3 m, for example, the permissible deflection is 1 cm For adhesive and product recommendations, see material releases.

With a live load (qk) $\leq 2.0 \text{ kN/m}^2$ and individual load (Qk) $\leq 1.0 \text{ kN}$, the following insulation thicknesses are permissible: Additional insulation EPS DEO 200 kPa max. 40 mm (max. layers: 2) Additional insulation XPS DEO 300 kPa max. 70 mm (max. layers: 2) Additional insulation XPS DEO 500 kPa max. 100 mm (max. layers: 2) With a live load (qk) $\leq 2.0 \text{ kN/m}^2$ and a concentrated load (Qk) $\leq 2.0 \text{ kN}$, the following insulation thicknesses are permissible: Additional insulation EPS DEO 200 kPa max. 20 mm (max. layers: 1) Additional insulation XPS DEO 300 kPa max. 30 mm (max. layers: 1) Additional insulation XPS DEO 500 kPa max. 40 mm (max. layers: 1)

Bond system elements / material layers to each other and to the substrate over the entire surface.

When using levelling fill, only the bonded fillings CF THERM PU and CF THERM CE are permissible as levelling. No other fillings (loose or bound) are permitted. CF THERM PU/CE can be bonded with tile adhesive.

The specifications of the permissible individual load (Qk) refer to a load area of at least 20 cm² (compression die \emptyset = 5 cm). Levelling compounds with reduced load-bearing behaviour are marked in the material releases.

